

## AMENDMENTS TO THE CLAIMS

## 1-22. (cancelled)

5    23. (previously presented): A light emitting diode, comprising at least:  
a substrate;  
a reflective layer formed over the substrate;  
a first reaction layer formed over said reflective layer;  
a transparent adhesive layer formed over said first reaction layer;  
10    a second reaction layer formed over said transparent adhesive layer;  
and an LED stack formed over said second reaction layer;  
wherein each of the first and second reaction layers is formed to enhance an  
adhesion provided by the transparent adhesive layer;  
wherein said transparent adhesive layer comprises at least a material selected from  
15    the group consisting of polyimide (PI), benzocyclobutene (BCB), and  
perfluorocyclobutane (PFCB); and  
wherein each said first and second reaction layers comprises at least a material  
selected from the group consisting of SiNx, Ti, and Cr.

20    24. (previously presented): A light emitting diode according to claim 23, further  
comprising a transparent conductive layer between said second reaction layer and  
said LED stack.

25    25. (previously presented): A light emitting diode according to claim 23, wherein said  
reflective layer is a reflective metal layer.

26. (cancelled)

27. (previously presented): A light emitting diode according to claim 25, wherein said  
30    reflective metal layer comprises at least a material selected from the group  
consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn,  
and AuZn.

28-43. (cancelled)

44. (previously presented): A light emitting diode, comprising at least:

- 5 a reflective means;
- a first reaction layer formed over said reflective means;
- a transparent adhesive layer formed over said first reaction layer;
- a second reaction layer formed over said transparent adhesive layer; and
- an LED stack formed over said second reaction layer;
- 10 wherein the first and second reaction layers enhance adhesion provided by the transparent adhesive layer,
- wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB); and
- 15 wherein each said first and second reaction layers comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

45. (previously presented): A light emitting diode, comprising at least:

- a substrate;
- 20 a reflective layer disposed on the substrate;
- a first reaction layer formed on said reflective layer;
- a transparent adhesive layer formed directly on said first reaction layer, said first reaction layer adhering to the transparent adhesive layer;
- a second reaction layer formed directly on said transparent adhesive layer, said second reaction layer adhering to the transparent adhesive layer; and
- 25 an LED stack formed over said second reaction layer,
- wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB); and
- 30 wherein each said first and second reaction layers comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

46. (cancelled)

47. (previously presented): A light emitting diode according to claim 45, further comprising a transparent conductive layer between said second reaction layer and  
5 said LED stack.

48. (previously presented): A light emitting diode according to claim 45, wherein said reflective layer is a reflective metal layer.

10 49. (previously presented): A light emitting diode according to claim 48, wherein said reflective metal layer comprises at least a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.

15 50-51. (cancelled)

52 (new): A light emitting diode according to claim 23, wherein said reflective layer is a reflective oxide layer.

20 53 (new): A light emitting diode according to claim 52, wherein said reflective oxide layer comprises at least a material selected from the group consisting of SiNx, SiO<sub>2</sub>, Al<sub>2</sub>O<sub>3</sub>, TiO<sub>2</sub>, and MgO.